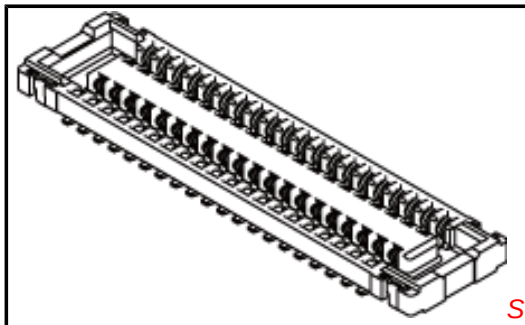
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PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: 5033044010
Status: Active
Overview: slimstack_mm016_pitch
Description: 0.40mm (.016") Pitch SlimStack™ Board-to-Board Receptacle, SMT, Dual Row, Vertical, 0.70mm (.028") Stacking Height, 40 Circuits



Series image - Reference only

Documents:

3D Model
Drawing (PDF)
Product Specification PS-503304-001 (PDF)
RoHS Certificate of Compliance (PDF)

General

Product Family	PCB Receptacles
Series	503304
Application	Board-to-Board
Overview	slimstack_mm016_pitch
Product Name	SlimStack™

Physical

Circuits (Loaded)	40
Color - Resin	Black
Durability (mating cycles max)	30
Glow-Wire Compliant	No
Lock to Mating Part	Yes
Mated Height (in)	0.028 In
Mated Height (mm)	0.70 mm
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Number of Rows	2
Orientation	Vertical
PCB Locator	No
PCB Retention	Yes
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface (in)	0.016 In
Pitch - Mating Interface (mm)	0.40 mm
Polarized to Mating Part	No
Polarized to PCB	No
Stackable	No
Temperature Range - Operating	-40°C to +85°C
Termination Interface: Style	Surface Mount

Electrical

Current - Maximum per Contact	0.3A
Voltage - Maximum	50V AC/DC

Material Info

Reference - Drawing Numbers

Application Specification	AS-503304-001
Packaging Specification	SPK-503304-001
Product Specification	PS-503304-001
Sales Drawing	SD-503304-001

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Not Reviewed
Halogen-Free Status
Not Reviewed

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

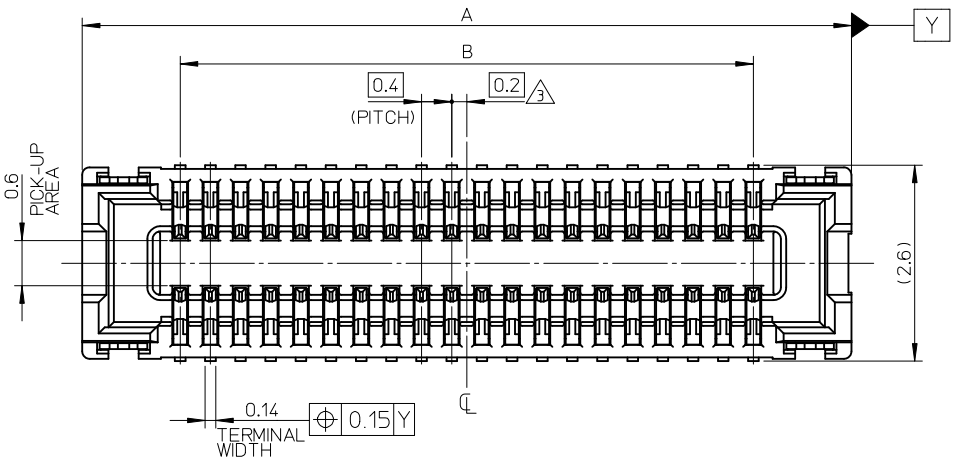
Please visit the Contact Us section for any non-product compliance questions.

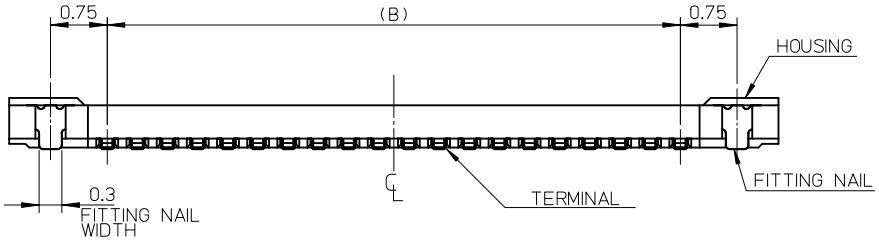
Search Parts in this Series
503304Series

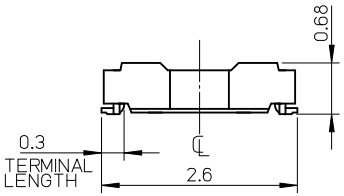
Mates With
503308 PCB Header

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PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION







注記 NOTES

1. 使用材料 MATERIAL
   ハウジング ：液晶ポリマー (LCP) UL94V-0 (黒)
   HOUSING:LIQUID CRYSTAL POLYMER UL94V-0 (COLOR:BLACK)
   ターミナル ：銅合金
   TERMINAL : COPPER ALLOY
   金具：銅合金
   FITTING NAIL : COPPER ALLOY
2. メッキ仕様 PLATING
   ターミナル TERMINAL
   金メッキ
   GOLD
   下地メッキ：ニッケルメッキ
   UNDER PLATING : NICKEL
   ※コンタクト部とテール部はニッケルメッキによって分断されている金メッキです.
   DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT AND THE TAIL PART BY THE NICKEL PLATING.
   金具 FITTING NAIL
   錫メッキ
   Tin PLATING
   下地メッキ：ニッケルメッキ
   UNDER PLATING : NICKEL
3. (全極数／ 2) =偶数の場合に適用.
   APPLY FOR (CIRCUIT/2)=EVEN.
4. 嵌合相手： 503308 シリーズ
   MATE WITH : 503308 SERIES.
5. テール平坦度は、 0.08 以下
   テール及び金具の平坦度は、 0.1 以下
   TAIL COPLANARITY TO BE 0.08MAXIMUM.
   TAIL AND FITTING NAIL COPLANARITY TO BE 0.1MAXIMUM.
6. ELV and RoHS COMPLIANT.

B	A	EMBOSSED PACKAGE / オーダー番号 ORDER No.	極数 CIRCUITS
11.6	14.2	503304-6010	60
9.6	12.2	503304-5010	50
8.4	11.0	503304-4410	44
8.0	10.6	503304-4210	42
7.6	10.2	503304-4010	40
5.6	8.2	503304-3010	30
4.8	7.4	503304-2610	26
3.6	6.2	503304-2010	20
3.2	5.8	503304-1810	18
2.8	5.4	503304-1610	16
2.0	4.6	503304-1210	12

CONNECTOR SERIES No. : 503304-**09

REVISED
EC NO: J2010-1761
DRWN:MTAKAHASHI 03 2009/12/23
CH'KD:THIRATA 2010/03/17
APPR:MSASAO 2010/03/18
DESCRIPTION
G
REV.

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±1 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 15:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: KSASAKI DATE: 2008/04/17
CHECKED BY: THIRATA DATE: 2008/04/17
APPROVED BY: M.SASAO DATE: 2008/04/17

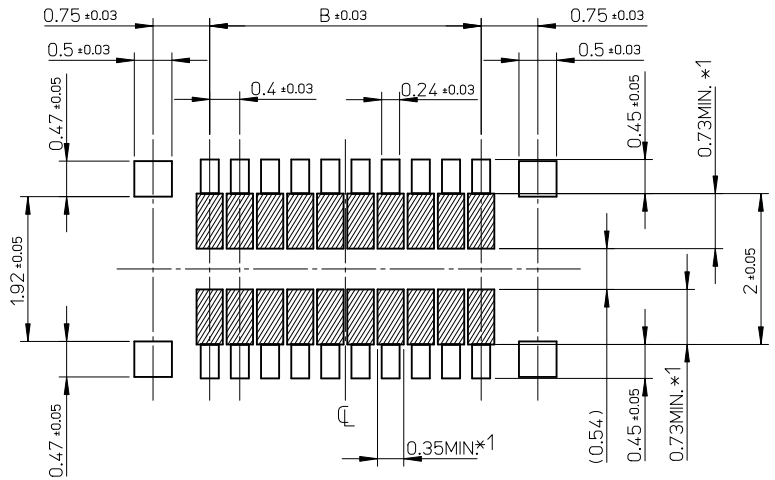
TITLE: 0.4 B-TO-B CONN. HGT=0.7 W=2.6 REC. ASS'Y

MOLEX INCORPORATED

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-503304-001
SHEET NO.: 1 OF 2

SIZE A3

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RECOMMENDED P.W. BOARD PATTERN LAYOUT

*1 パターン引き回し、および半田禁止エリア
（当該箇所においては、これと接する回路以外の配線を禁止する．
また、接する回路を配線する場合はレジストを施し、この部分に
半田は無きこととする．）

*1 PROHIBITED AREA OF PATTERN WIRING AND SOLDER.
(FOR EACH AREA, THE WIRING THAT TOUCHES ON THE SOLDER CAN BE ATTACHED, THEN COVERED WITH A FILM TO KEEP SOLDER OUT.)

REVISED			REV	DESCRIPTION
EC NO: J2010-1761	DRWN:MTAKAHASHI03	2009/12/23		
	CHKD:THIRATA	2010/03/17		
	APPR:MSASAO	2010/03/18		
	G			

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±1 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	15:1
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	KSASAKI
DATE	2008/04/17
CHECKED BY	THIRATA
DATE	2008/04/17
APPROVED BY	M.SASAO
DATE	2008/04/17
MATERIAL NO.	SEE CHART
TITLE	0.4 B-TO-B CONN. HGT=0.7 W=2.6 REC. ASS'Y
	MOLEX INCORPORATED
DOCUMENT NO.	SD-503304-001
SHEET NO.	2 OF 2
SIZE	A3

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